

**APPLICATIONS:**

- Pager
- PDA
- Set Top Box
- Cellular Phone

# LRS13012

## Stacked Chip

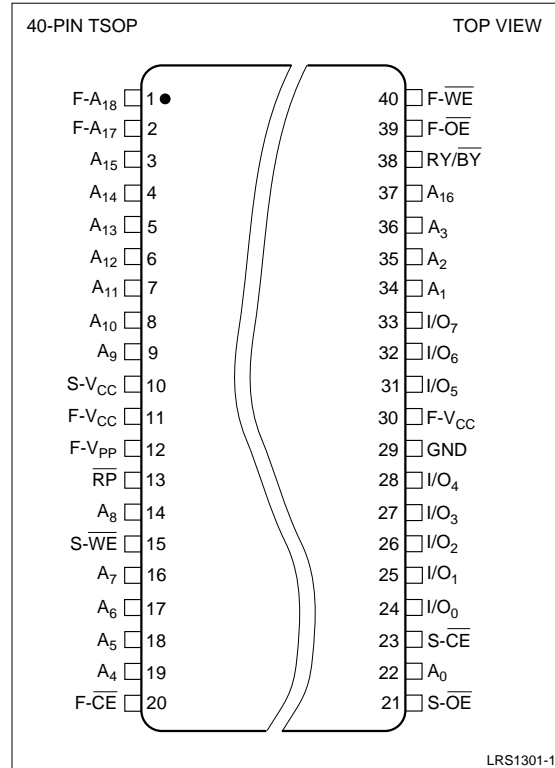
**FEATURES**

- 4M Flash and 1M SRAM
- Flash memory access time 150 ns MAX.
- SRAM access time 70 ns MAX.
- Operating current
  - Flash memory read 12 mA MAX. ( $t_{CYCLE} = 200$  ns)
  - Flash byte write 40 mA MAX.
  - Flash block erase 37 mA MAX.
  - SRAM operating 25 mA MAX. ( $t_{CYCLE} = 200$  ns)
- Standby current
  - Flash memory 20  $\mu$ A MAX.  
( $F-\overline{CE} \geq V_{CC} - 0.2$  V,  $RP \leq 0.2$  V)
  - SRAM 30  $\mu$ A MAX. ( $S-\overline{CE} \geq V_{CC} - 0.2$  V)  
0.3  $\mu$ A TYP. ( $T_A = 25^\circ$ C,  $V_{CC} = 3$  V,  $S-\overline{CE} \geq V_{CC} - 0.2$  V)
  - Total standby current is the summation of flash memory's standby current and SRAM's standby current
- Power supply 2.7 V to 3.6 V. (Block erase, byte write and lock-bit configuration operations with  $V_{CC} < 3.0$  V are not supported)
- SRAM data retention current 1  $\mu$ A MAX.  
( $V_{CCDR} = 3$  V,  $T_A = 25^\circ$ C)
- Operating temperature  $-40^\circ$ C to  $+85^\circ$ C
- Fully static operation
- Three-state output
- Not designed or rated as radiation hardened
- 40-pin TSOP (TSOP40-P-0813) plastic package
- Flash Memory has P-type bulk silicon, and SRAM has N-type bulk silicon

**DESCRIPTION**

The LRS13012 is a combination memory organization as 524,288  $\times$  8 bit flash memory and 131,072  $\times$  8 bit static RAM in one package. It is fabricated using silicon-gate CMOS process technology.

**40-PIN TSOP PINOUT**



**PIN DESCRIPTION**

PIN	DESCRIPTION
A <sub>0</sub> to A <sub>16</sub>	Common Address Input Pins
F-A <sub>17</sub> to F-A <sub>18</sub>	Address Input Pins for Flash Memory
F-CE	Chip Enable Input Pin for Flash Memory
S-CE	Chip Enable Input Pin for SRAM
F-WE	Write Enable Input Pin for Flash Memory
S-WE	Write Enable Input Pin for SRAM
F-OE	Output Enable Input Pin for Flash Memory
S-OE	Output Enable Input Pin for SRAM
I/O <sub>0</sub> to I/O <sub>7</sub>	Common Data Input/Output Pins
RP	Reset/Deep Power Down Input Pin for Flash Memory
RY/BY	Ready/Busy Output Pin for Flash Memory
F-V <sub>CC</sub>	Power Supply Pin for Flash Memory
F-V <sub>PP</sub>	Power Supply for Flash Memory Write/Erase
S-V <sub>CC</sub>	Power Supply Pin for SRAM
GND	Common GND

The information for this document is from Specification No. EL103011, issued on March 3, 1998.